<b>1</b> 2	ТУР	#	Hit	Search Text	DBs	Time Stamp	C o o B Error Definition t t
Н	BRS ]	L1	0	(Krul-Johannes.in. Hart-Cornelius-Maria.in. DeLeeuw-Dagobert-Michel.in. DeHesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20040224	USPAT; US-PGPUB; EPO; JPO	2004/06/23	
2 B	BRS 1	L2	2	•	DERWENT	2004/06/23 13:56	
З	BRS ]	L3	∞		USPAT; US-PGPUB	2004/06/23 13:57	
4 B	BRS I	L4	2	) near5 (IC (integrated)) same (organic 20040224	USPAT; US-PGPUB	2004/06/23 13:59	
Б	BRS I	L5	0	((paper cardboard currency passport) near5 (ic chip semiconduct\$3)) same (security near2 (strip thread)) and @pd>20040224	USPAT; US-PGPUB	2004/06/23 13:59	
В	BRS I	L6	н	port) and and	USPAT; US-PGPUB	2004/06/23 14:00	
7 B	BRS I	Ь7	0	24	USPAT; US-PGPUB	2004/06/23 14:03	
8 B	BRS I	L8	1	trip	USPAT; US-PGPUB	2004/06/23 14:03	
<u>в</u>	BRS I	L9	Н	<pre>(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram) and @pd&gt;20040224</pre>	USPAT; US-PGPUB	2004/06/23 14:04	

	Тур	#	Hit	Search Text	DBs	Time Stamp	B Error Definition or r
10	BRS	L10	Р	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram holographic) and @pd>20040224	USPAT; US-PGPUB	2004/06/23 14:05	
11	BRS	Lll	2	near2 (strip thread)) same holographic) and @pd>20040224	USPAT; US-PGPUB	2004/06/23 14:06	
12	BRS	L12	4	ency passport) duct\$3)) same ontact) e capacitive) and	USPAT; US-PGPUB	2004/06/23 14:06	
13	BRS	L13	Н	(ic circuit semiconductive semiconductor) same polyimide same polyaniline and @pd>20040224	USPAT; US-PGPUB	2004/06/23 14:07	
14	BRS :	L14	2	(organic near2 polymer) same polyimide	USPAT; US-PGPUB	2004/06/23 14:08	
15	BRS:	L15	Ъ	iconductive same (polyimide adj10 d @pd>20040224	USPAT; US-PGPUB	2004/06/23 14:09	
16	BRS :	L16	4	polyimide adj10 polyaniline and [@pd>20040224 [	USPAT; US-PGPUB	2004/06/23 14:09	
17	BRS	L17	ω	(security near2 (strip thread)) same (size thickness width thick) and @pd>20040224	USPAT; US-PGPUB	2004/06/23 14:10	
18	BRS ]	L18	29	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) l same (IC chip circuit semiconductor l semiconducting) and @pd>20040224	USPAT; US-PGPUB	2004/06/23 14:12	

bank adj note\$1) passport (document\$1 paper\$1 \$1)) same (IC chip nductor semiconducting)) \$1 (bank adj note\$1) rity adj1 (document\$1 e (IC chip circuit semiconducting)) and ank adj note\$1) passport (document\$1 paper\$1 (document\$1 paper\$1 (document\$1 paper\$1 (document\$1 paper\$1 (ic circuit\$1) chip near5 (organic carbon pnear5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; circuit\$1) chip near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; circuit\$1) chip near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; circuit\$1) chip near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; circuit\$1) chip near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; circuit\$1) chip near5 (organic carbon) 2 and @pd>20040224 ibility bend\$4) near5 (ic cuspan; circuit\$1) chip near5 (organic carbon) DERWENT;	DBs Time Stamp  assport \$1 \$1 p ting)) USPAT; 2004/06/23 t\$1 US-PGPUB 14:20  ssport \$1 DERWENT; \$1 ar5 (ic USPAT; ar5 (ic USPAT; US-PGPUB 14:21 ar5 (ic USPAT; ar5 (ic USPAT; ar5 (ic USPAT; 14:31 ar5 (ic EPO; JPO; 2004/06/23 rbon) LEPO; JPO; 2004/06/23 rbon) LEPO; JPO; 2004/06/23 rbon LEPO; JPO; 2004/06/23 rbon LEPO; JPO; 2004/06/23 rbon LEPO; JPO; 2004/06/23	24 BRS L24 3 (in ser	23 BRS L23 1 (in	22 BRS L22 1 (i) set	21 BRS L21 15 (i) sei	20 BRS L20 15 thre	(() (s) (th (ci) no pa pa (@p)	Typ L # Hit
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	Set De 日日   Set De	2004/06/23	2004/06/23 14:32	2004/06/23 14:31	2004/06/23	2004/06/2	2004/06/23 14:20	Stamp

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L25 0 (flexible flexibility bend\$4) near5 (ic USPAT; 2004/06/23 semiconductor) near5 paper and (flexible flexibility bend\$4) near5 (ic USPAT; 2004/06/23 semiconductor) near5 paper and (flexible flexibility bend\$4) near5 (ic USPAT; 2004/06/23 semiconductive) near5 organic and (USPAT; 2004/06/23 semiconductor) near5 (ic chip semiconductor) near5 (ic EPO; JPO; 2004/06/23 semiconductor) near5 (ic chip semiconductor) uSPAT; 14:42 semiconductor) near5 (ic chip semiconductor) and (USPAT; 2004/06/23 semiconductor) near5 (ic chip semiconductor) near5 (USPAT; 2004/06/23 semicond		_	0	9	8		6	υ U	
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Hit s  Search Text  DBS Time Stamp   Representation   Report   2004/06/23   Remiconductor) near5 paper and   USPAT;   2004/06/23   Remiconductor) near5 paper and   USPAT;   2004/06/23   Remiconductive) near5 organic and   USPAT;   2004/06/23   Remiconductive) near5 paper and   USPAT;   2004/06/23   Remiconductive) near5 paper and   USPAT;   2004/06/23   Remiconductor)   Remiconductor   USPAT;   2004/06/23   Remiconductor)   Remiconductor   USPAT;   2004/06/23   Remiconductor)   Remiconductor   Repo; JPO;   2004/06/23   Remiconductor   Repo; JPO;   2004/06/23   Remiconductor	L32	L31	L30	L29	L28	L27	L26	L25	
flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 paper and (gpd>2004/06/23 semiconductor) near5 paper and (ground) uspaT; (ic (integrated adj circuit\$1) semiconductor (integrated adj circuit\$1) semiconduc	508	Ъ	ω	0	0	N	·И		
Time Stamp e Error n t t t t t t t t t t t t t t t t t t	(340/572.8.ccls. 257/774.ccls. 257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.) and @pd>20040224	near5 (ic chip semiconductor) near5 enna coil) near5 print\$3 and 20040224	near5 (ic chip semiconductor) (antenna coil) and @pd>20040224	near5 paper near5 (ic chip iconductor) near5 (antenna coil) and >20040224	ibility bend\$4) near5 (ic j circuit\$1) near5 paper and	<pre>xible flexibility bend\$4) near5 (ic egrated adj circuit\$1) semiconductor conductive) near5 organic and 20040224</pre>	exibility bend\$4) near5 (ic adj circuit\$1) semiconductor ve) near5 organic and	exibility bend\$4) near5 (ic adj circuit\$1) r) near5 paper and	Search
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1	BRS	Ľ1	0	in. us.in. @pd>20040623	USPAT; US-PGPUB; EPO; JPO	2004/07/01	
2	BRS	L2	0	(Krul-J.in. Hart-C.in. DeLeeuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20040623	DERWENT	2004/07/01 15:20	
ω	BRS	L3	0	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (thread strip security forgery authentic\$3) and @pd>20040623	USPAT; US-PGPUB	2004/07/01 15:20	
4	BRS	L4	0	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (organic polymer) and @pd>20040623	USPAT; US-PGPUB	2004/07/01 15:22	
5	BRS	Г2	0	y passport) t\$3)) same read)) and	USPAT; US-PGPUB	2004/07/01 15:23	
6	BRS	16	0	((paper cardboard currency passport) near5 (ic chip semiconduct\$3)) and (security near2 (strip thread)) and @pd>20040623	USPAT; US-PGPUB	2004/07/01 15:23	
7	BRS	L7	0	y passport) t\$3)) same nd @pd>20040623	USPAT; US-PGPUB	2004/07/01 15:23	
ω	BRS	L8	0	trip	USPAT; US-PGPUB	2004/07/01 15:24	
9	BRS	L9	0	y near2 (strip ptical\$2 foil 3	USPAT; US-PGPUB	2004/07/01 15:24	

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Typ L # Hit s    Conduct\$3 near5 (security near2 (strip thread))   Same   Conduct\$3   Sam	. 0		2004/07/01 15:35	USPAT; US-PGPUB	nk adj note (document\$1 ircuit semi and @pd>20	N	L18		18
Typ L # Hit s Search Text DBs Time Stamp Re Error Definition    Conduct\$3 neax5 (security neax2 (strip thread)) and (hologram optical\$2 foil thread)) and (hologram optical\$2 foil US-PGPUB 15:24    RRS L11	0		2004/07/01 15:35	USPAT; US-PGPUB	near2 (strip thread)) kness width thick) and 323		Ь17		17
Typ L #   Hit   Search Text   DBs   Time Stamp   Error Definition   Typ   L #   Hit   Search Text   DBs   Time Stamp   Error Definition   Typ	0		2004/07/01 15:34	USPAT; US-PGPUB	polyaniline		L16		16
### ### Search Text DBs Time Stamp   Error Definition   Error Definiti	0		2004/07/01 15:34	; ;			L15		15
Typ L # Hit s Search Text DBs Time Stamp H Error Definition    Conduct\$3 near5 (security near2 (strip thread)) and (holographic) and @pd>20040623   USPAT;   2004/07/01	0		100	USPAT; US-PGPUB	nic near2 popolyaniline	0	L14	BRS	14
Typ L # Hit s Search Text DBs Time Stamp e Error Definition    Rest   L10	0		2004/07/01 15:33	USPAT; US-PGPUB			Ь13		13
Hit s Search Text DBs Time Stamp e Error Definition  (conduct\$3 near5 (security near2 (strip kinegram holographic) and @pd>20040623 US-PGPUB 15:24  BRS L11 1 (security near2 (strip thread)) same USPAT; 2004/07/01 (hologram holographic) and @pd>20040623 US-PGPUB 15:25	0		2004/07/01 15:25	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconduct\$3)) same (noncontact (non adj contact) contactlessly inductive capacitive) and @pd>20040623		L12	BRS	12
Typ L # Hit Search Text DBs Time Stamp e Error Definition    Conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil thread))) and (hologram optical\$2 foil thread))) and (hologram optical\$2 foil thread)) and wholographic) and @pd>20040623 US-PGPUB   15:24	0		2004/07/01 15:25		623		L11		11
Hit Search Text DBs Time Stamp e Error Definition t	0		2004/07/01 15:24	and	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram holographic) and @pd>20040623		017	BRS	10
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	2004/07/01 15:47	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20040623	0	BRS L25	24 1
	2004/07/01	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20040623	0	BRS L24	23
	2004/07/01	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20040623	0	BRS L23	22
	2004/07/01 15:42	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20040623	ω ω	BRS L22	21 1
	2004/07/01 15:41	EPO; JPO; DERWENT; IBM_TDB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20040623	0	BRS L21	20 1
	2004/07/01 15:41	USPAT; US-PGPUB	((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting)) not ((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting)) and @pd>20040623	0	BRS L20	19 1
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0		2004/07/01 15:50	USPAT; US-PGPUB	(340/572.8.ccls. 257/774.ccls. 257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 283/92.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.) and	5 N	L33	BRS	28
0		2004/07/01 15:49	USPAT; US-PGPUB	tag near5 (ic chip semiconductor) near5 (antenna coil) near5 print\$3 and @pd>20040623	0	L32	BRS	31
0		2004/07/01 15:49	USPAT; US-PGPUB	r5 (ic cenna	<del>اسا</del>	L31	BRS	0.5
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0		2004/07/01 15:48	EPO; JPO; DERWENT; IBM_TDB	\$4) near5 (ic semiconductor nic and	0	L28	BRS	27
0		2004/07/01 15:47	USPAT; US-PGPUB	bend\$4) near5 ( [t\$1) semiconduc organic and	Н	L27	BRS	26
0		2004/07/01 15:47	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 paper and @pd>20040623	0	L26	BRS	25
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